

Application Serial No. 10/628,651
Amendment dated May 31, 2005

AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A solid brazing component having a liquidus temperature above 840°F selected from the group consisting of wire, strip, foil and preforms, wherein the brazing component is made of an alloy consisting essentially of, in weight percent:

- (a) about 4-9% phosphorus;
- (b) about 0.1-10% tin;
- (c) about 0.1-15% nickel;
- (d) about 0.1-18% silver;
- (e) up to about 3% silicon;
- (f) up to about 4% antimony;
- (g) up to about 3% manganese; and

the balance copper.

2-4. Canceled.

5. (Original) The component of claim 1 wherein the brazing component has a liquidus temperature less than about 1410°F and a solidus temperature less than about 1100°F.

6. (Currently Amended) The component of claim 5 wherein the alloy consists essentially of:

- (b) about 4-8% tin; and
- (c) about 5-8% nickel[.];
- (d) about 1-18% silver; and
- (e) about 0.001-0.1% silicon.

7. (Original) The component of claim 6 wherein the alloy exhibits a major thermal arrest at a temperature below about 1250°F.

Application Serial No. 10/628,651
Amendment dated May 31, 2005

8-13. Canceled.

14-21. Canceled.

22. (Previously Presented) A solid brazing component having a liquidus temperature above 840°F selected from the group consisting of wire, strip, foil and preforms, wherein the brazing component is made of an alloy consisting essentially of, in weight percent:

- (a) about 4-9% phosphorus;
- (b) about 0.1-10% tin;
- (c) about 0.1-15% nickel;
- (d) up to about 18% silver;
- (e) about 0.001-3% silicon;
- (f) up to about 4% antimony;
- (g) up to about 3% manganese; and

the balance copper.

23-24. Canceled.

25. (Previously Presented) The component of claim 22 wherein the alloy consists essentially of:

- (c) about 5-8% nickel.

26-34. Canceled.

Application Serial No. 10/628,651
Amendment dated May 31, 2005

35. (New) A solid brazing component having a liquidus temperature above 840°F selected from the group consisting of: wire, strip, foil and preforms, wherein the brazing component is made of an alloy consisting essentially of, in weight percent:

- (a) about 4-10% phosphorus;
- (b) about 0.1-8% tin;
- (c) about 0.001-3% silicon;
- (d) up to about 3% nickel;
- (e) up to about 18% silver;
- (f) up to about 4% antimony;
- (g) up to about 3% manganese; and

the balance copper, with the proviso that the sum of tin and antimony does not exceed about 10%.

36. (New) The component of claim 35 wherein the brazing component has a liquidus temperature less than about 1300°F and a solidus temperature less than about 1200°F.

37. (New) The component of claim 35 wherein the alloy consists essentially of:

- (a) about 6-7% phosphorus;
- (b) about 2-8% tin;
- (c) about 0.001-0.1% silicon;
- (f) up to about 2% antimony; and

the balance copper.

38. (New) The component of claim 37 wherein the alloy exhibits a major thermal arrest at a temperature below about 1275°F.

Application Serial No. 10/628,651
Amendment dated May 31, 2005

39. (New) A fluxless solid brazing component having a liquidus temperature above 840°F selected from the group consisting of: wire, strip, foil and preforms, wherein the brazing component consists of, in weight percent:

- (a) about 4-10% phosphorus;
- (b) about 0.1-8% tin;
- (c) about 0.001-3% silicon;
- (d) up to about 3% nickel;
- (e) up to about 18% silver;
- (f) up to about 4% antimony;
- (g) up to about 3% manganese; and

the balance copper, with the proviso that the sum of tin and antimony does not exceed about 10%.

40. (New) The component of claim 39 wherein the brazing component has a liquidus temperature less than about 1300°F and a solidus temperature less than about 1200°F.

41. (New) The component of claim 39 wherein the brazing component consists of:

- (a) about 6-7% phosphorus;
- (b) about 2-8% tin;
- (c) about 0.001-0.1% silicon;
- (f) up to about 2% antimony; and

the balance copper.

42. (New) The component of claim 41 wherein the alloy exhibits a major thermal arrest at a temperature below about 1275°F.